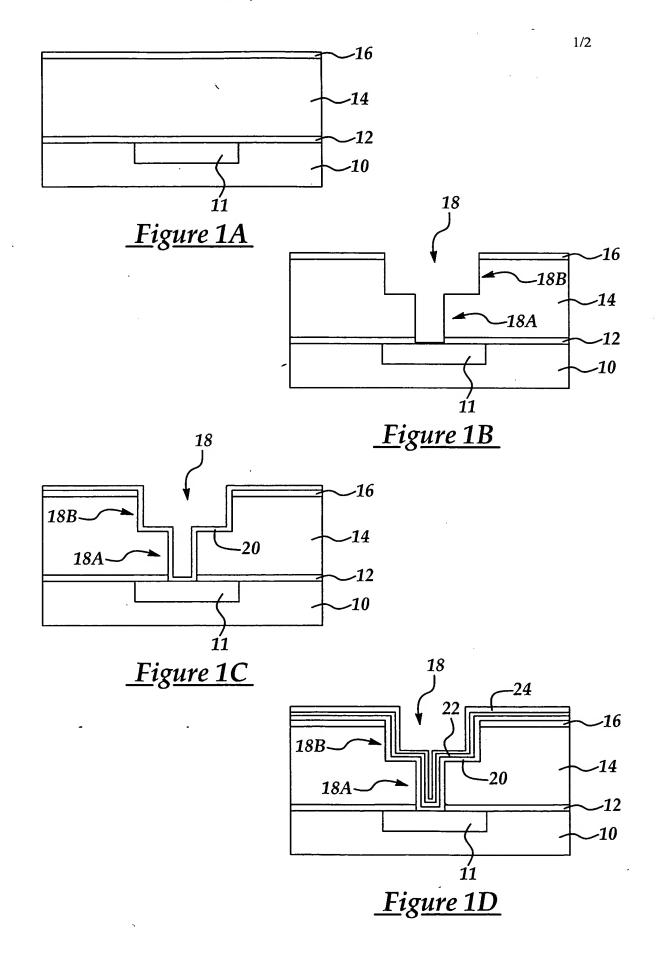
Inventor: Ping-Kun Wu

Serial No.: To Be Assigned Filed: Herewith

For: Method For Forming A Multi-Layer-Seed Layer For Improved CU ECP

Attorney Doc. No.: 67,200-1190

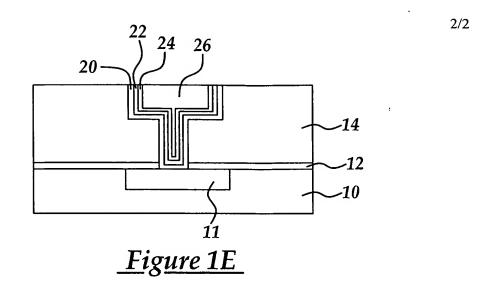


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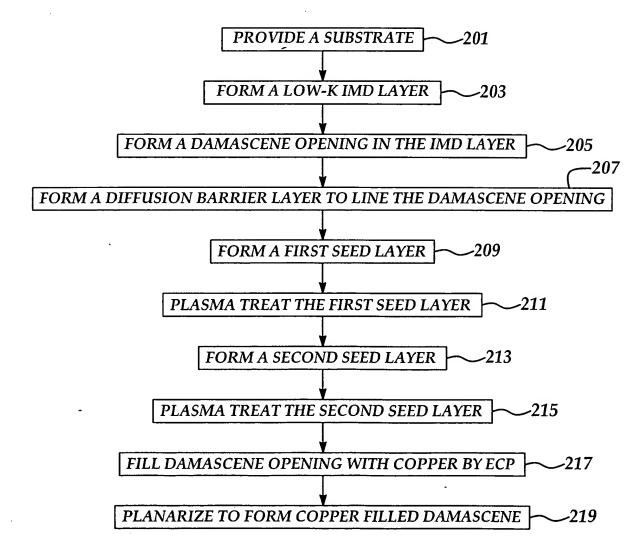


Figure 2